

#### **Features**

- □ Small size of 1812
- □ Lead-free and compliant with the European Union RoHS Directive 2011/65/EU
- □ Fast tripping resettable circuit protection
- □ Surface mount packaging for automated assembly
- ☐ Agency Recognition: UL、CSA、TUV





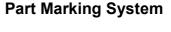
Product family



## **Product Dimensions (mm)**

	(11111)					
Part number —	Α	В	С	D	E	
	Max.	Max.	Max.	Min.	Min.	
LP-MSM014	4.73	3.41	1.00	0.30	0.30	





Current rating

Electrical C	haracte	ristics					ŭ		
Dout woudhou	I <sub>H</sub>	Ι <sub>Τ</sub>	$V_{max}$	I <sub>max</sub>	T <sub>trip</sub>		Pd <sub>typ</sub>	R <sub>min</sub>	R <sub>1max</sub>
Part number -	(A)	(A)	(V)	(A)	Current(A)	Time(S)	(W)	(Ω)	(Ω)
LP-MSM014	0.14	0.34	60	10	1.5	0.15	1.0	1.50	6.00

I<sub>H</sub>=Hold current: maximum current at which the device will not trip at 25℃ still air.

I<sub>T</sub>=Trip current: minimum current at which the device will always trip at 25°C still air.

V<sub>max</sub>=Maximum voltage device can withstand without damage at rated current.

I<sub>max</sub>=Maximum fault current device can withstand without damage at rated voltage.

 $T_{trip}$ =Maximum time to trip(s) at assigned current.

Pd<sub>typ</sub>=Typical power dissipation: typical amount of power dissipated by the device when in state air environment.

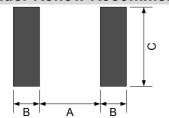
R<sub>min</sub>=Minimum device resistance at 25℃ prior to tripping.

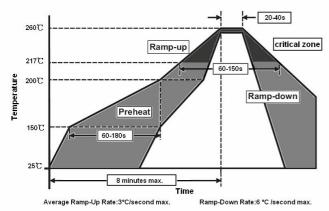
R<sub>1max</sub>=Maximum device resistance measured in the nontripped state 1 hour post reflow.

# **Thermal Derating**

Thermal Berating										
LP-MSM014	Maximum ambient operating temperature(℃)									
	-40	-20	0	20	25	40	50	60	70	85
Hold Current (A)	0.23	0.20	0.18	0.16	0.14	0.12	0.11	0.10	0.07	0.05
Trip Current (A)	0.48	0.44	0.40	0.36	0.34	0.28	0.26	0.24	0.18	0.12

#### **Solder Reflow Recommendations**





## Solder Pad Layouts

Part number -	Α	В	С
Fait ilullibei –	(mm)	(mm)	(mm)
LP-MSM014	3.45	1.78	3.15

- \* Recommended reflow methods: IR, Vapor phase, hot air oven.
- \* Devices can be cleaned using standard industry methods and solvents.

### Notes:

- If reflow temperatures exceed the recommended profile, devices may not meet the performance requirements.
- Devices are not designed to be wave soldered to the bottom side of the board.

#### **Package Information**

Tape & Reel: 2000pcs per reel.

Effectivity: Reference documents shall be the issue in effect on the date of invitation for bid.

Caution: Operation beyond the rated voltage or current may result in rupture electrical arcing or flame. Specifications are subject to change without notice.

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